

## Reliability Qualification Plan for LFCSP package at STATS ChipPAC China (SCC)

QUALIFICATION PLAN			
Test	Conditions	Sample Size	Expected Completion Date
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	<b>3 x 45</b>	April 2014
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	<b>3 x 45</b>	April 2014
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	<b>3 x 45</b>	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	<b>3 x 11</b>	April 2014
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	<b>1 x 45</b>	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	<b>3/Voltage</b>	April 2014

\*Preconditioned per JEDEC/IPC J-STD-020